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(12) **United States Design Patent** (10) **Patent No.:** **US D933,618 S**
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(54) **SEMICONDUCTOR MODULE**

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(52) **U.S. Cl.**
USPC **D13/182**

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See application file for complete search history.

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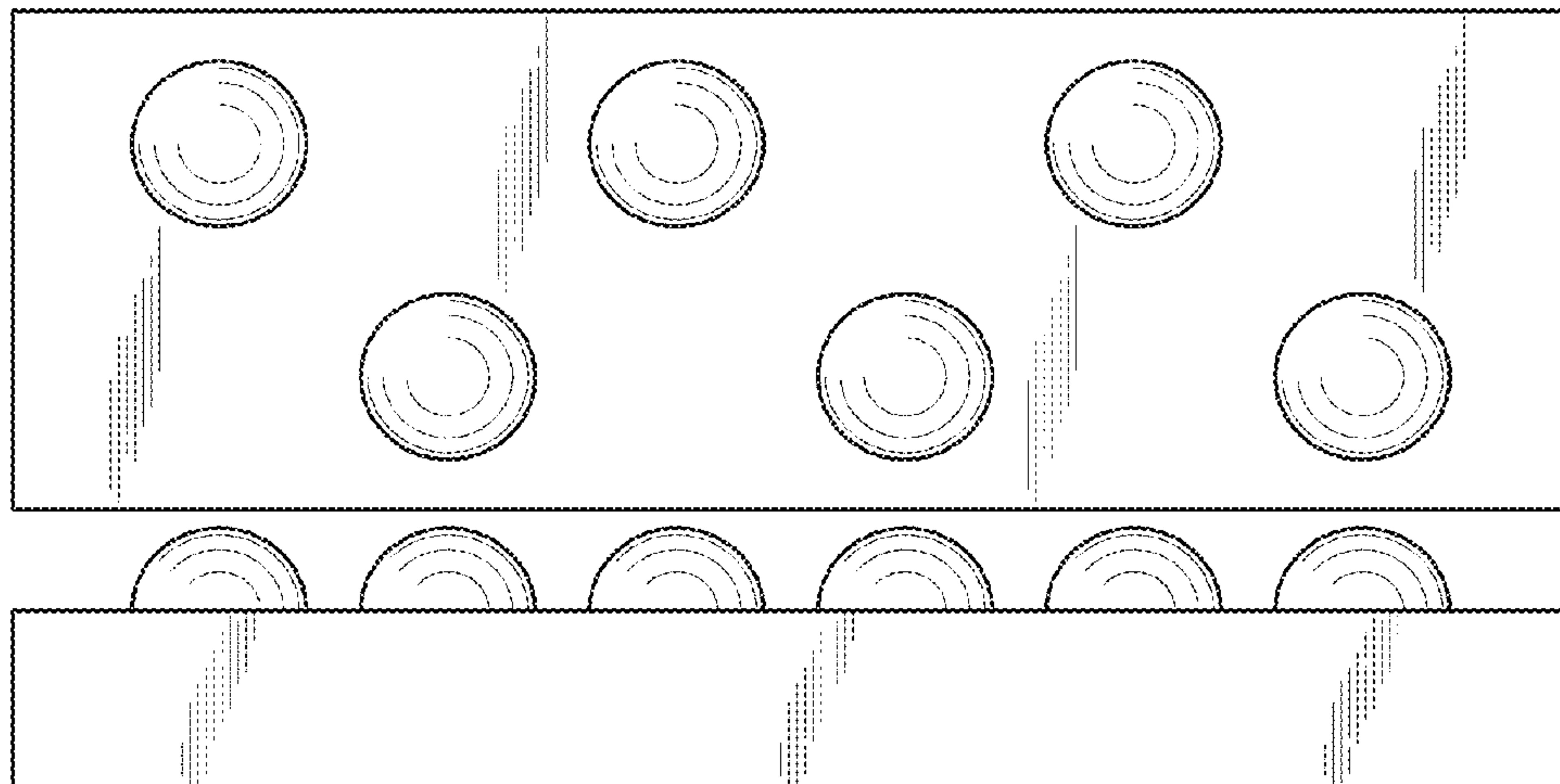
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a semiconductor module showing our new design;
FIG. 2 is a rear view of the semiconductor module thereof;
FIG. 3 is a left view of the semiconductor module thereof;
FIG. 4 is a right view of the semiconductor module thereof;
FIG. 5 is a top side view of the semiconductor module thereof; and,
FIG. 6 is a bottom side view of the semiconductor module thereof.

(Continued)



The thinner lines other than a thicker line in the front view, the rear view, the left side view the right side view, the top view, and the bottom view represents a shape of a three-dimensional shape.

1 Claim, 6 Drawing Sheets

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FIG. 1

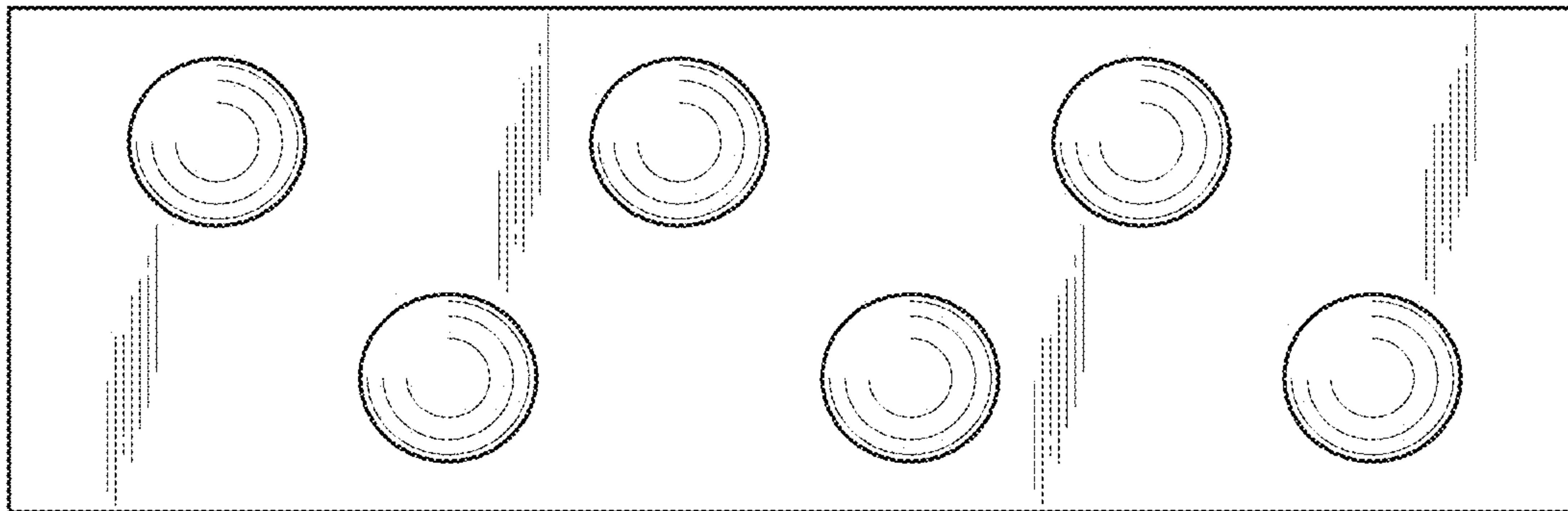


FIG.2

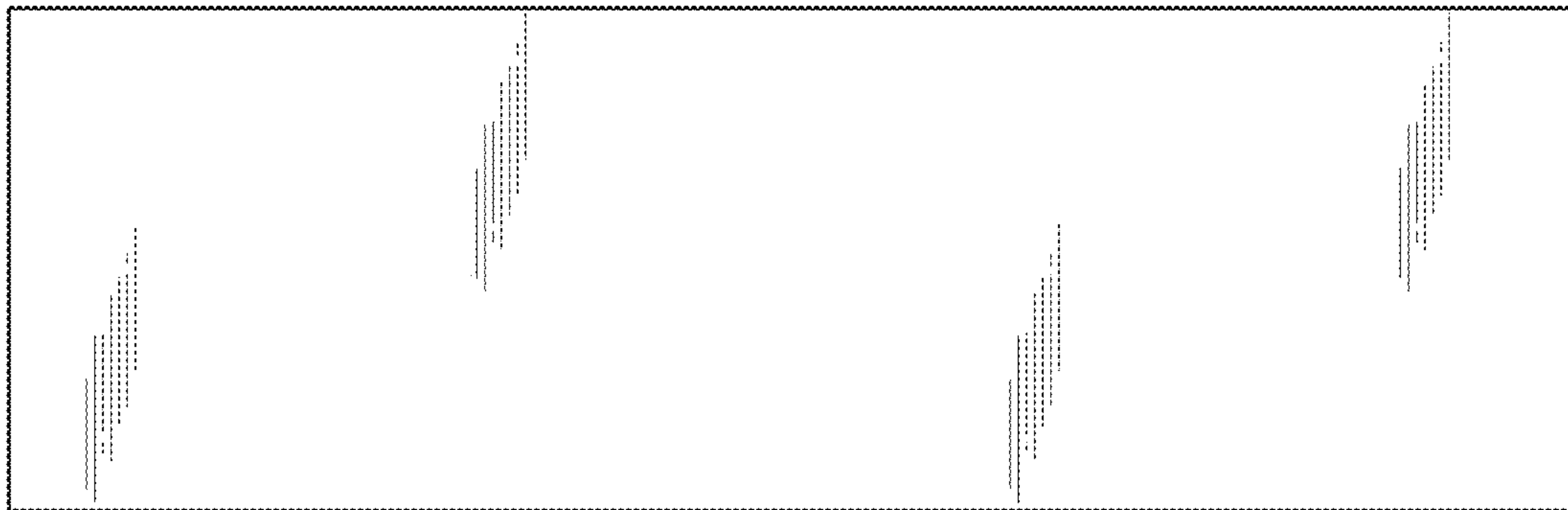


FIG.3

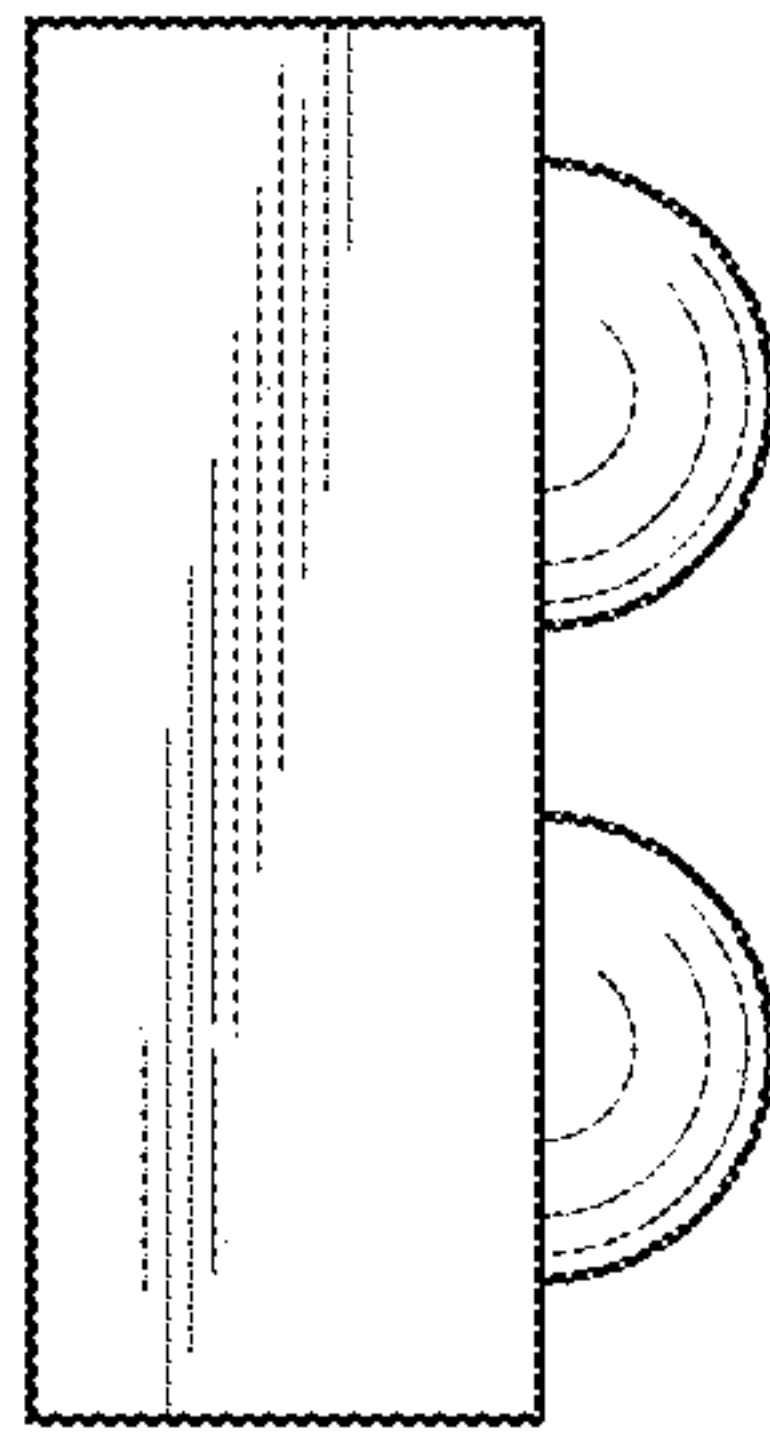


FIG.4

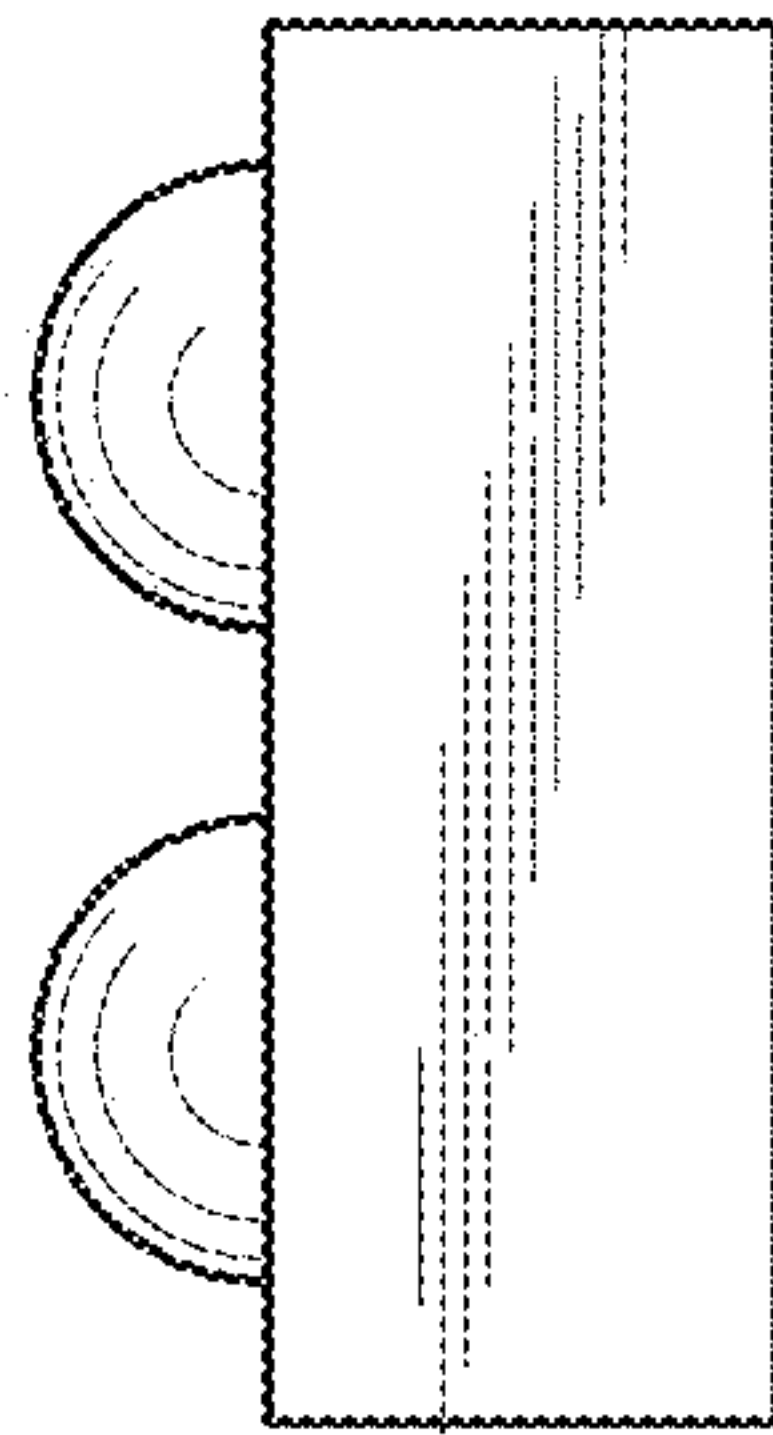


FIG.5

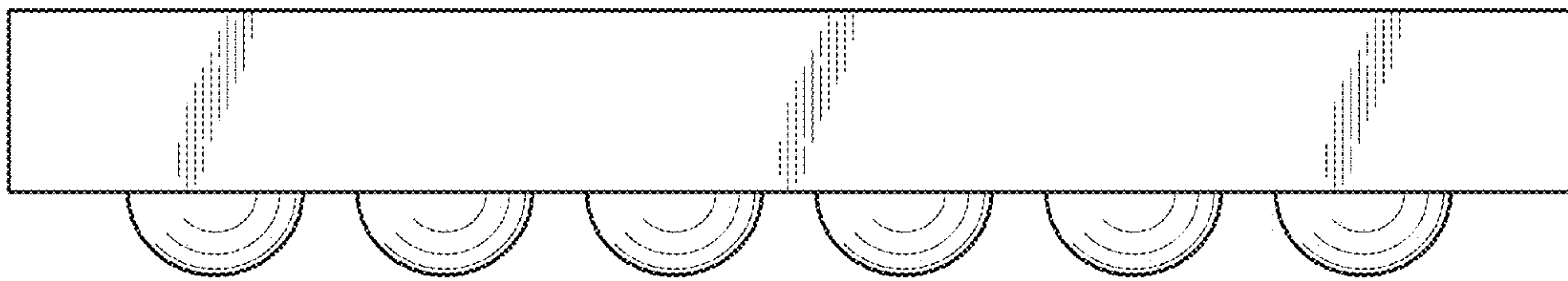


FIG.6

